LiPOLY®
SHIU LI TECHNOLOGY CO.,LTD

DTT61-s

Immersion Cooling Thermal Conductive Pad

LiPOLY DTT61-s is a material designed for immersion cooling gap filling. It has passed Engineered Fluids' materials compatibility testing and received the highest level of certification. The thermal conductivity is 6.0 W/m*K with high flexibility, high insulating, which can cover the tolerance of design making it very stable. It also offers customized shape molding service.

FEATURES

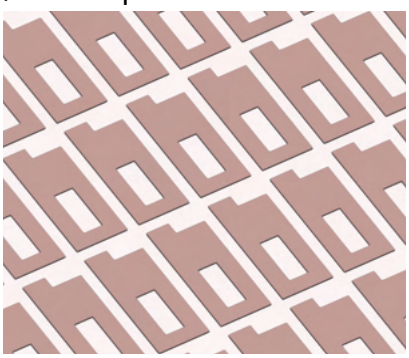
/ Thermal conductivity: 6.0 W/m*K
/ Naturally tacky for ease of manufacture
/ Low thermal impedance
/ Available in a range of thicknesses

TYPICAL APPLICATION

/ Single-phase Immersion Cooling of Servers
/ Gaming PC
/ AI PC
/ Solid State Drive(SSD)
/ Heat pipe assemblies
/ Memory modules
/ Power amplifiers

SPECIFICATIONS

/ Roll form / Sheet form
/ Die-cut parts



TYPICAL PROPERTIES

PROPERTY	DTT61-s	TEST METHOD	UNIT
Color	Red	Visual	-
Surface tack 2-side/1-side	2	-	-
Thickness	Customized	ASTM D374	mm
Density	3.3	ASTM D792	g/cm³
Application temperature	-60~200	-	°C
ROHS & REACH	Compliant	-	-
COMPRESSION@1.0mm			
Deflection @10 psi	4	ASTM D5470 modify	%
Deflection @20 psi	5	ASTM D5470 modify	%
Deflection @30 psi	8	ASTM D5470 modify	%
Deflection @40 psi	14	ASTM D5470 modify	%
Deflection @50 psi	19	ASTM D5470 modify	%
ELECTRICAL			
Dielectric breakdown	8	ASTM D149	KV/mm
Surface resistivity	$>10^{11}$	ASTM D257	Ohm
Volume resistivity	$>10^{10}$	ASTM D257	Ohm-m
THERMAL			
Thermal Conductivity	6.0	ASTM D5470	W/m*K
Thermal impedance@10 psi	0.387	ASTM D5470	°C-in²/ W
Thermal impedance@20 psi	0.375	ASTM D5470	°C-in²/ W
Thermal impedance@30 psi	0.356	ASTM D5470	°C-in²/ W
Thermal impedance@40 psi	0.333	ASTM D5470	°C-in²/ W
Thermal impedance@50 psi	0.317	ASTM D5470	°C-in²/ W

Thermal Impedance vs. Pressure vs. Deflection